

## 30V/6A Synchronous Step-Down Converter

### Features

- Wide 4.0V to 30V Operating Input Range
- 6.0A Continuous Output Current
- Switching Frequency: 250, 300, 400 (KHz)
- 0.8VFB PFM & CCM
- Short Protection with Hiccup-Mode
- Built-in Over Current Limit
- Integrated internal Soft-Start
- 25/18mΩ Low  $R_{DS(ON)}$  Internal MOSFETs
- Output Adjustable from 0.8V
- Low EMI Signature
- 100% Duty cycle max
- Integrated internal compensation
- Thermal Shutdown
- Available in ESOP8 Package
- Constant on time Mode

### General Description

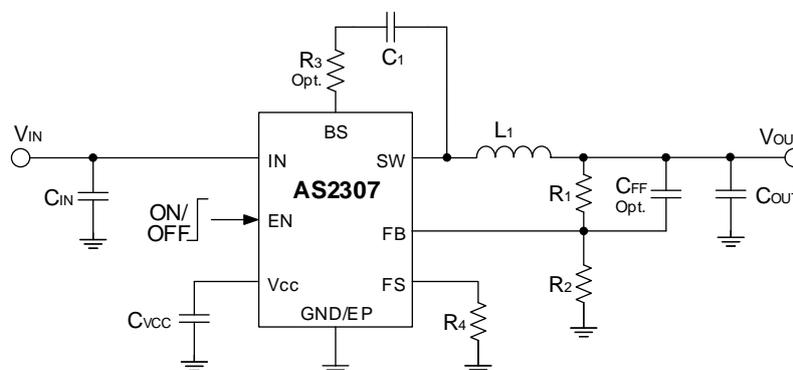
The AS2307 is a low EMI signature, asynchronous, step-down, switch-mode converter with internal power MOSFETs. It offers a very compact solution to provide a 6A continuous current over a wide input supply range, with excellent load and line regulation. AS2307 achieves low EMI signature with well controlled switching edges. Fault condition protection includes programmable-output over-voltage protection, Constant on time Mode, and thermal shutdown.

AS2307 requires a minimal number of readily available standard external components. It is available in ESOP8 package.

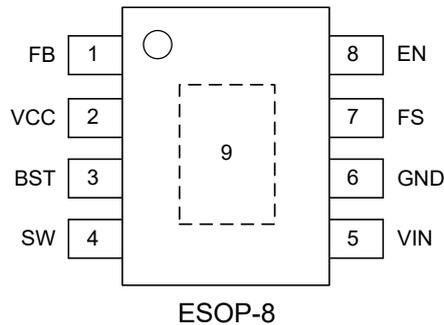
### Applications

- Automotive Entertainment
- Wireless and DSL Modems
- Computer Entertainment
- Power Supply for Car Chargers

### Typical Application Circuit



## Pin Configuration



## Pin Descriptions

Pin	Name	Function
1	FB	Adjustable Version Feedback input. Connect FB to the center point of the external resistor divider
2	VCC	1.0uF/6.3V capacitor connected between VCC and GND
3	BST	Bootstrap. A capacitor connected between SW and BS pins is required to form a floating supply across the high-side switch driver.
4	SW	Switching Pin
5	VIN	Power Supply Pin
6	GND	Ground Pin
7	FS	Switching Frequency Set
8	EN	Drive this pin to a logic-high to enable the IC. Drive to a logic-low to disable the IC and enter micro-power shutdown mode.
9	EPAD	Ground Pin

## Ordering Information

PART No.	PACKAGE	Logo	Tape&Reel
AS2307	ESOP-8	AS2307	3000pcs/reel

## Recommended Operating Conditions

Item	Min	Max	Unit
Operating junction temperature <sup>(1)</sup>	-40	125	°C
Operating temperature range	-40	85	°C
Input voltage $V_{IN}$	4.5	28	V
Output current (5.0V $V_{out}$ )	0	6	A

Note (1). All limits specified at room temperature ( $T_A = 25^\circ\text{C}$ ) unless otherwise specified. All room temperature limits are 100% production tested.

## Absolute Maximum Ratings (1) (2)

Item	Min	Max	Unit
V <sub>IN</sub> voltage	-0.3	32	V
EN voltage	-0.3	32	V
SW voltage	-0.3(-5V<10nS)	V <sub>IN</sub> +0.5V(+35V<10nS)	V
BST voltage		V <sub>SW</sub> +5	V
FB voltage	-0.3	6.5V	V
Power dissipation <sup>(3)</sup>		1.7	W
Operating junction temperature, T <sub>J</sub>	-40	150	°C
Storage temperature, T <sub>stg</sub>	-65	150	°C
Lead Temperature (Soldering, 10sec.)		260	°C

Note (1): Exceeding these ratings may damage the device.

Note (2): The device is not guaranteed to function outside of its operating conditions.

Note (3): The maximum allowable power dissipation is a function of the maximum junction temperature, T<sub>J(MAX)</sub>, the junction-to-ambient thermal resistance, R<sub>θJA</sub>, and the ambient temperature, T<sub>A</sub>. The maximum allowable power dissipation at any ambient temperature is calculated using: P<sub>D(MAX)</sub> = (T<sub>J(MAX)</sub> - T<sub>A</sub>) / R<sub>θJA</sub>. Exceeding the maximum allowable power dissipation causes excessive die temperature, and the regulator goes into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage. Thermal shutdown engages at T<sub>J</sub>=160°C (typical) and disengages at T<sub>J</sub>= 130°C (typical).

## ESD Ratings

Item	Description	Value	Unit
V <sub>(ESD-HBM)</sub>	Human Body Model (HBM) ANSI/ ESDA/JEDEC JS-001-2014 Classification, Class: 2	±2000	V
V <sub>(ESD-CDM)</sub>	Charged Device Mode (CDM) ANSI/ ESDA/JEDEC JS-002-2014 Classification, Class: C0b	±200	V
I <sub>LATCH-UP</sub>	JEDEC STANDARD NO.78E APRIL 2016 Temperature Classification, Class: I	±150	mA

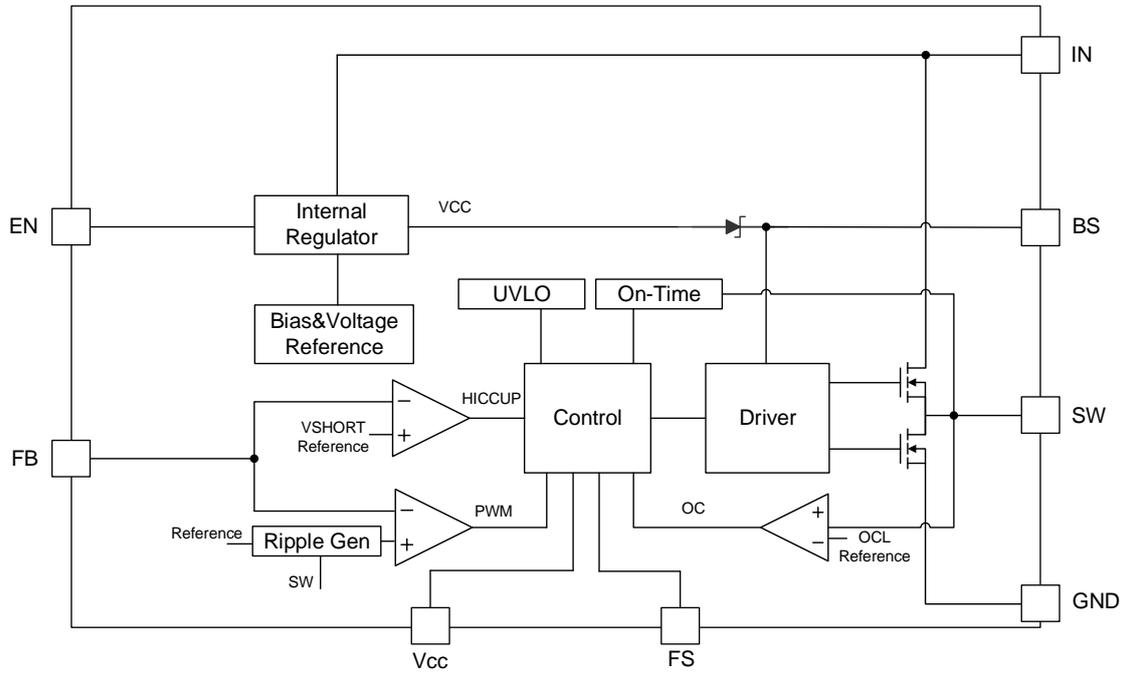
## Thermal Information

Item	Description	Value	Unit
R <sub>θJA</sub>	Junction-to-ambient thermal resistance <sup>(1)(2)</sup>	48.7	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	52.4	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	25.5	°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	8.4	°C/W
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	25.2	°C/W

Note (1): The package thermal impedance is calculated in accordance to JESD 51-7.

Note (2): Thermal Resistances were simulated on a 4-layer, JEDEC board

## Functional Block Diagram



## Electrical Characteristics (1) (2)

$V_{IN}=20V$ ,  $T_A=25^{\circ}C$ , unless otherwise specified.

Parameter	Conditions	Min.	Typ.	Max.	Unit
Input Voltage Range		4.0		30	V
Over Voltage Protection Threshold			33		V
Quiescent current into VIN pin/CCM	$V_{IN} = 20V$ , Out = 5V, Iload = 0A		15	30	mA
Quiescent current into VIN pin/PFM	$V_{IN} = 20V$ , Out = 5V, Iload = 0A		350	430	$\mu A$
Shutdown current into VIN pin	$V_{EN} = 0V$ , $V_{IN} = 20V$			3	$\mu A$
Regulated Feedback Voltage	$V_{IN} = 20V$ , $T_A = 25^{\circ}C$	784	800	816	mV
Output Voltage Line Regulation	$V_{IN} = 4.5V$ to 30V			1	%
Output Voltage Load Regulation	$V_{IN} = 20V$ , Out = 5V, $\Delta V_{LOAD}(0-4.0)$			1	%
Oscillation Frequency1	$V_{IN} = 20V$ , Out = 5V, Iload = 1A	200	250	350	KHz
Frequency & Mode set	FS=PGND, PFM 250 KHz		250		KHz
	FS=30K, PFM 300 KHz		300		KHz
	FS=75K, PFM 400 KHz		400		KHz
	FS=150K, CCM 400 KHz		400		KHz
	FS=270K, CCM 300 KHz		300		KHz
	FS= Float, CCM 250 KHz		250		KHz
High-Side Switch On-Resistance	$I_{SW} = 1000mA$		25		$m\Omega$
Low-Side Switch On-Resistance	$I_{SW} = -1000mA$		18		$m\Omega$
High-Side Switch Current Limit	$V_{IN} = 20V$ , FB = 90%		9		A
Low-Side Switch Current Limit	$V_{IN} = 20V$ , FB = 90%		7		A
$V_{IN}$ Under-Voltage Lockout Threshold			3.5		V
$V_{IN}$ Under-Voltage Lockout Threshold-Hysteresis			300		mV
EN Rising Threshold		1.5			V
EN Falling Threshold				0.4	V
EN Threshold Hysteresis			200		mV
EN Leakage Current				1.0	$\mu A$
SW Leakage Current	$V_{EN} = 0V$ , $V_{IN} = V_{SW} = 30V$			1.0	$\mu A$
Soft Start		3	6	10	mS
Thermal Shutdown			165		$^{\circ}C$
Thermal Hysteresis			30		$^{\circ}C$

Note (1): MOSFET on-resistance specifications are guaranteed by correlation to wafer level measurements.

Note (2): Thermal shutdown specifications are guaranteed by correlation to the design and characteristics analysis.

## Functions Description

### Internal Regulator

The AS2307 is a constant on time mode step down DC/DC converter that provides excellent transient response with no extra external compensation components. This device contains an internal, low resistance, high voltage power MOSFET, and operates at a high 250KHz operating frequency to ensure a compact, high efficiency design with excellent AC and DC performance.

### Error Amplifier

The error amplifier compares the FB pin voltage with the internal FB reference ( $V_{FB}$ ) and outputs a current proportional to the difference between the two. This output current is then used to charge or discharge the internal compensation network, which is used to control the power MOSFET current. The optimized internal compensation network minimizes the external component counts and simplifies the control loop design.

### Under-Voltage Lockout (UVLO)

Under-voltage lockout (UVLO) protects the chip from operating at an insufficient supply voltage. UVLO protection monitors the internal regulator voltage. When the voltage is lower than UVLO threshold voltage, the device is shut off. When the voltage is higher than UVLO threshold voltage, the device is enabled again.

### Thermal Shutdown

Thermal shutdown prevents the chip from operating at exceedingly high temperatures. When the silicon die temperature exceeds 160°C, it shuts down the whole chip. When the temperature falls below its lower threshold (Typ. 160°C) the chip is enabled again.

### Internal Soft-Start

The soft-start is implemented to prevent the converter output voltage from overshooting during startup. When the chip starts, the internal circuitry generates a soft-start voltage (SS) ramping up from 0V to 0.8V. When it is lower than the internal reference (REF), SS overrides REF so the error amplifier uses SS as the reference. When SS is higher than REF, REF regains control. The SS time is internally max to 1.5ms.

### Startup and Shutdown

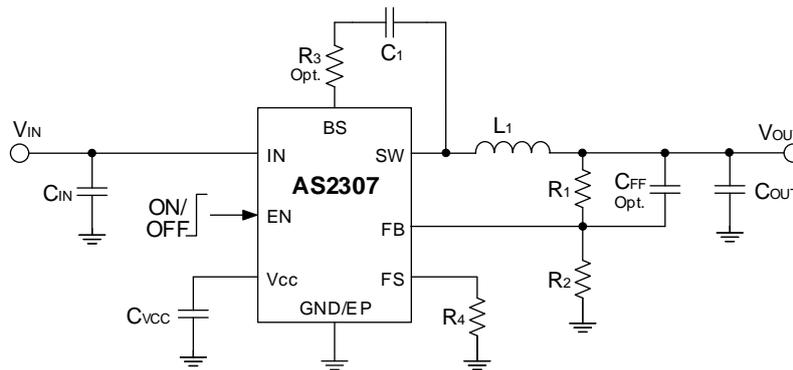
If both  $V_{IN}$  and EN are higher than their appropriate thresholds, the chip starts. The reference block starts first, generating stable reference voltage and currents, and then the internal regulator is enabled. The regulator provides stable supply for the remaining circuitries. Three events can shut down the chip: EN low,  $V_{IN}$  low and thermal shutdown. In the shutdown procedure, the signaling path is first blocked to avoid any fault triggering. The comp voltage and the internal supply rail are then pulled down. The floating driver is not subject to this shutdown command.

## Applications Information

### Setting the Output Voltage

AS2307 require an input capacitor, an output capacitor and an inductor. These components are critical to the performance of the device. AS2307 are internally compensated and do not require external components to achieve stable operation. The output voltage can be programmed by resistor divider.

$$V_{OUT} = V_{FB} \times \frac{R1 + R2}{R2}$$



V <sub>OUT</sub>	R1	R2	L1	C1	C <sub>VCC</sub>	C <sub>IN</sub>	C <sub>OUT</sub>	C <sub>FF Opt.</sub>
3.3V	47KΩ 1%	15KΩ 1%	2.2-4.7μH 10A	>10V 0.1uF X5R	>6.3V 1uF	10uF X5R	22uF*2 X5R	10-100pF
5.0V	43KΩ 1%	8.2KΩ 1%	2.2-10μH 10A	>10V 0.1uF X5R	>6.3V 1uF	10uF X5R	22uF*2 X5R	10-100pF
12V	43KΩ 1%	3K 1%	6.8-15μH 10A	>10V 0.1uF X5R	>6.3V 1uF	10uF X5R	22uF*2 X5R	10-100pF

R3 default= 0Ω

R4 default= NC(250KHz Mode=CCM) Frequency set :

Frequency & Mode set	FS	Mode	Frequency (KHz)
	FS=PGND	PFM	250 KHz
	FS=30K	PFM	300 KHz
	FS=75K	PFM	400 KHz
	FS=150K	CCM	400 KHz
	FS=270K	CCM	300 KHz
	FS= Float	CCM	250 KHz

### Selecting the Inductor

The recommended inductor values are shown in the Application Diagram. It is important to guarantee the inductor core does not saturate during any foreseeable operational situation. The inductor should be rated to handle the maximum inductor peak current: Care should be taken when reviewing the different saturation current ratings that are specified by different manufacturers. Saturation current ratings are typically specified at 25°C, so ratings at maximum ambient temperature of the application should be requested from the manufacturer. The inductor value can be calculated with:

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times \Delta I_L \times F_{OSC}}$$

Where  $\Delta I_L$  is the inductor ripple current. Choose inductor ripple current to be approximately 30% if the maximum load current. The maximum inductor peak current is:

$$I_{L(MAX)} = I_{LOAD} + \frac{\Delta I_L}{2}$$

Under light load conditions below 100mA, larger inductance is recommended for improved efficiency.

### **Selecting the Output Capacitor**

Special attention should be paid when selecting these components. The DC bias of these capacitors can result in a capacitance value that falls below the minimum value given in the recommended capacitor specifications table. The ceramic capacitor's actual capacitance can vary with temperature. The capacitor type X7R, which operates over a temperature range of  $-55^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$ , will only vary the capacitance to within  $\pm 15\%$ . The capacitor type X5R has a similar tolerance over a reduced temperature range of  $-55^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$ . Many large value ceramic capacitors, larger than 1uF are manufactured with Z5U or Y5V temperature characteristics. Their capacitance can drop by more than 50% as the temperature varies from  $25^{\circ}\text{C}$  to  $85^{\circ}\text{C}$ . Therefore X5R or X7R is recommended over Z5U and Y5V in applications where the ambient temperature will change significantly above or below  $25^{\circ}\text{C}$ . Tantalum capacitors are less desirable than ceramic for use as output capacitors because they are more expensive when comparing equivalent capacitance and voltage ratings in the 0.47uF to 44uF range. Another important consideration is that tantalum capacitors have higher ESR values than equivalent size ceramics. This means that while it may be possible to find a tantalum capacitor with an ESR value within the stable range, it would have to be larger in capacitance (which means bigger and more costly) than a ceramic capacitor with the same ESR value. It should also be noted that the ESR of a typical tantalum will increase about 2:1 as the temperature goes from  $25^{\circ}\text{C}$  down to  $-40^{\circ}\text{C}$ , so some guard band must be allowed.

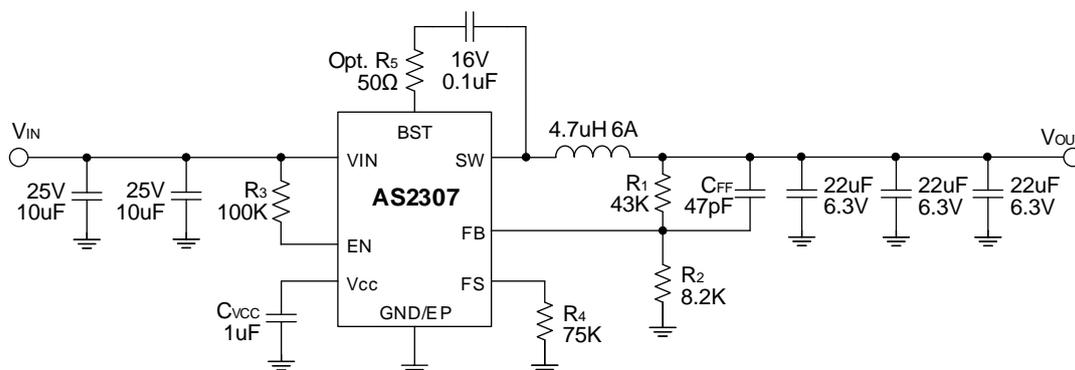
## PC Board Layout Example & Guidelines

The PCB layout is an important step to maintain the high performance of the AS2307 device.

1. The input/output capacitors and the inductor should be placed as close as possible to the IC. This keeps the power traces short. Routing these power traces direct and wide results in low trace resistance and low parasitic inductance.
2. The low side of the input and output capacitors must be connected properly to the power GND to avoid a GND potential shift.
3. The sense traces connected to FB are signal traces. Special care should be taken to avoid noise being induced. Keep these traces away from SW nodes.
4. GND layers might be used for shielding.

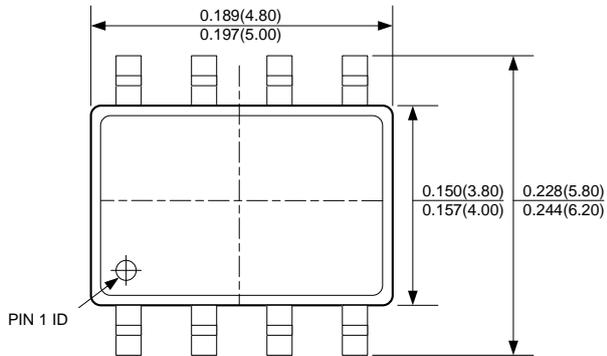
## Recommended Application Circuit

VIN=DC5-20V Vout=5V Iout=4A Below: (存在热插拨的应用场景时, 输入端需要加大于600W 的 TVS {SMBJ 系列 SMBJ20CA}, 防止过大的浪涌电压损坏芯片, TVS 添加后可以去掉输入的电解电容)  
R4=75K—频率=400KHz, 模式为DCM, IQ=430uA Max, 占空比=100% (上管导通)。

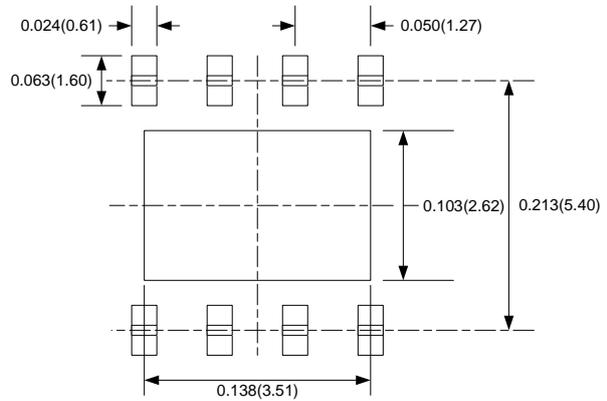


## Package Information

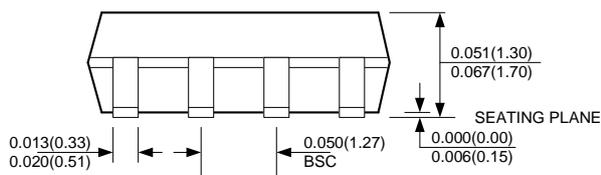
### ESOP-8



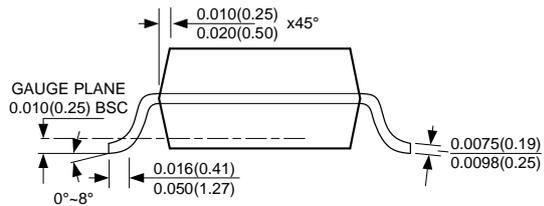
**TOP VIEW**



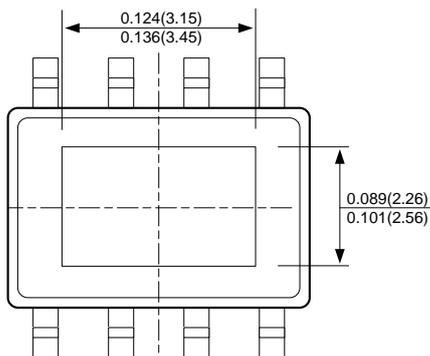
**RECOMMENDED PAD LAYOUT**



**FRONT VIEW**



**SIDE VIEW**



**BOTTOM VIEW**

**NOTE:**

1. CONTROL DIMENSION IS IN INCHES. DIMENSION IN BRACKET IS IN MILLIMETERS.
2. PACKAGE LENGTH DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
3. PACKAGE WIDTH DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSIONS.
4. LEAD COPLANARITY (BOTTOM OF LEADS AFTER FORMING) SHALL BE 0.004" INCHES MAX.
5. DRAWING CONFORMS TO JEDEC MS-012, VARIATION BA.
6. DRAWING IS NOT TO SCALE.